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SyChip Interface ASIC Supports SD and SDIO Functions; New design allows OEMs To Offer Multiple Functions in a Single Network Interface Card --NIC-- and Module

PLANO, Texas--(BUSINESS WIRE)--Sept. 27, 2004--SyChip, a leader in Radio Frequency Chip Scale Modules (CSM) and System in Package (SIP) technology for the wireless mobile market, today announced the completion of its next-generation interface technology to provide combination functions in a single SDIO card or module design. This capability can be seen in next-generation designs offered by SyChip's customers and partners and will address key needs for new usage models for PDAs, smart phones, feature phones, digital cameras, media devices and other SDIO enabled devices.

"The addition of this capability for multiple functions to be managed by our interface technology marks another leap forward by SyChip in the SDIO card and wireless module market," said Moses Asom, co-founder and senior vice president of marketing and business development, SyChip. "By adding multi-function capability to a single bus, users will now be able to download and store or upload large files such as high resolution photos, MP3 files and video streams with a single card that combines memory and I/O functions.

Having the ability to combine popular single functions, such as wireless connectivity and flash memory, for portable devices, SyChip is able to design multi-function SDIO cards at lower prices than are currently available by purchasing the devices separately. This capability also allows for enhanced performance of such functions through the effective management of each function from an interference and performance perspective.

The SyChip multi-function interface technology has been rigorously tested for interoperability with several peripheral devices on several handheld products from leading manufacturers that are targeted for major wireless service providers. Through SyChip's customers and partners, such solutions will be sold through online and through retail locations in the Americas, Europe and most of Asia.

For more information on the SyChip combo capability solution, please contact Navi Miglani at 972-202-8847 or nmiglani@sychip.com.

About SyChip, Inc.

SyChip designs, develops and markets Radio Frequency Integrated Circuits and Chip Scale Modules for the wireless mobile market. The company focuses on developing RF modules that are differentiated due to proprietary integration, modular architectures, and low loss Silicon technologies. As a result of the proprietary integration, world-class RF system design, proprietary multifunction ASICs, software and smart utilities. SyChip's RF designs drastically reduce component count, offer very small footprints and are easy to integrate into a mobile device. Customers benefit by significantly reducing their time-to-market, increasing performance and improving reliability of their wireless devices. In 2003 SyChip was awarded "Start-Up to Watch" by the Fabless Semiconductor Association (FSA), as well as being selected as Investors' Choice award winner at VentureWire's annual MicroVentures conference.

More information is available at www.sychip.com.

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